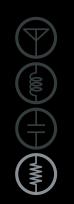


Innovative Service Around the Globe

DATA SHEET

LOW OHMIC CHIP RESISTORS RL series (Pb Free)

sizes 0402/0603/0805/1206/ 1210/1218/2010/2512







<u>SCOPE</u>

This specification describes RL0402 to RL2512 low ohmic chip resistors with lead-free terminations made by thick film process.

ORDERING INFORMATION

Part number is identified by the series, size, tolerance, packing type, temperature coefficient, taping reel and resistance value.

YAGEO ORDERING CODE

CTC CODE

RL XXXX X X X XX XXXX L

(1) (2) (3) (4) (5) (6)

(I) SIZE

0402	
0603	
0805	
1206	
1210	
1218	
2010	
2512	

(7)

(2) TOLERANCE

 $F = \pm 1\%$

 $J = \pm 5\%$

(3) PACKAGING TYPE

- R = Paper/PE taping reel
- K = Embossed taping reel

(4) TEMPERATURE COEFFICIENT OF RESISTANCE

- = Base on spec

(5) TAPING REEL

07 = 7 inch dia. Reel

(6) RESISTANCE VALUE

0R01, 0R056, 0R56, 0R91 of E24 series (E48/96 on request).

(7) RESISTOR TERMINATIONS

L = Lead free terminations (matte tin)

ORDERING EXAMPLE

The ordering code of a RL0805 chip resistor, value 0.56 Ω with ±1% tolerance, supplied in 7-inch tape reel is: RL0805FR-070R56L.

ΝΟΤΕ

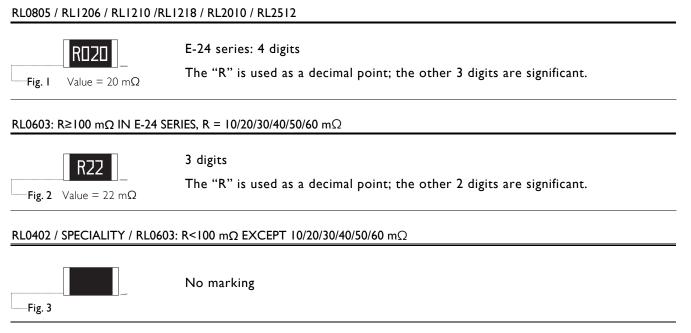
- The "L" at the end of the code is only for ordering. On the reel label, the standard CTC will be mentioned an additional stamp "LFP"= lead free production.
- 2. Products with lead in terminations fulfil the same requirements as mentioned in this datasheet.
- 3. Products with lead in terminations will be phased out in the coming months (before July 1st, 2006)





Chip Resistor Surface Mount

MARKING



For marking codes, please see EIA-marking code rules in data sheet "Chip resistors marking".

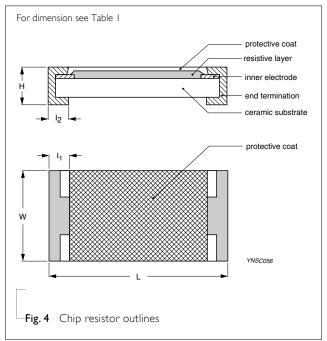
CONSTRUCTION

The resistors are constructed out of a high-grade ceramic body. Internal metal electrodes are added at each end and connected by a resistive paste. The composition of the paste is adjusted to give the approximate required resistance and laser cutting of this resistive layer that achieves tolerance trims the value. The resistive layer is covered with a protective coat and printed with the resistance value. Finally, the two external terminations (matte tin) are added. See fig. 4.

CONSTRUCTION

TYPE	L (mm)	W (mm)	H (mm)	l₁ (mm)	l₂ (mm)
RL0402	1.00 ±0.10	0.50 ±0.05	0.35 ±0.05	0.20 ±0.10	0.25 ±0.10
RL0603	1.60 ±0.10	0.80 ±0.10	0.45 ±0.10	0.25 ±0.15	0.25 ±0.15
RL0805	2.00 ±0.10	1.25 ±0.10	0.50 ±0.10	0.35 ±0.20	0.35 ±0.20
RL1206	3.10 ±0.10	1.60 ±0.10	0.55 ±0.10	0.45 ±0.20	0.40 ±0.20
RL1210	3.10 ±0.10	2.60 ±0.15	0.55 ±0.10	0.50 ±0.20	0.50 ±0.20
RL1218	3.05 ±0.15	4.60 ±0.20	0.55 ±0.10	0.45 ±0.25	0.50 ±0.25
RL2010	5.00 ±0.10	2.50 ±0.15	0.55 ±0.10	0.60 ±0.20	0.50 ±0.20
RL2512	6.35 ±0.10	3.20 ±0.15	0.55 ±0.10	0.60 ±0.20	0.50 ±0.20

OUTLINES



Chip Resistor Surface Mount RL SERIES 0402 to 2512 (Pb Free)

ELECTRICAL CHARACTERISTICS

Table 2

TYPE / RESISTANCE RANGE	TEMPERATURE COEFFICIENT OF RESISTANCE								
RL0402 ∣00mΩ≤R<∣Ω					100m0	Ω≤R <iω< th=""><th></th><th></th></iω<>			
		±800 ppm/°C							
RL0603 ∣0mΩ≤R<∣Ω	I0mΩ≤R≤36	mΩ	36n	nΩ <r< th=""><th>≤9ImΩ</th><th>91mΩ<i< th=""><th>R≤500mΩ</th><th>500mΩ<r<iω< th=""></r<iω<></th></i<></th></r<>	≤9ImΩ	91mΩ <i< th=""><th>R≤500mΩ</th><th>500mΩ<r<iω< th=""></r<iω<></th></i<>	R≤500mΩ	500mΩ <r<iω< th=""></r<iω<>	
KLUGUJ 10m(25K<102	±1,500 ppm	/°C	±Ι	,200 p	pm/°C	±800	ppm/°C	±300 ppm/°C	
	I0mΩ≤R≤I8mΩ	I8mΩ <r≤4< th=""><th>ł7mΩ</th><th>47mΩ</th><th>Ω<r≤9imω< th=""><th>91mΩ<r≤360mω< th=""><th>360mΩ<r≤500mω< th=""><th>500mΩ<r<iω< th=""></r<iω<></th></r≤500mω<></th></r≤360mω<></th></r≤9imω<></th></r≤4<>	ł7mΩ	47mΩ	Ω <r≤9imω< th=""><th>91mΩ<r≤360mω< th=""><th>360mΩ<r≤500mω< th=""><th>500mΩ<r<iω< th=""></r<iω<></th></r≤500mω<></th></r≤360mω<></th></r≤9imω<>	91mΩ <r≤360mω< th=""><th>360mΩ<r≤500mω< th=""><th>500mΩ<r<iω< th=""></r<iω<></th></r≤500mω<></th></r≤360mω<>	360mΩ <r≤500mω< th=""><th>500mΩ<r<iω< th=""></r<iω<></th></r≤500mω<>	500mΩ <r<iω< th=""></r<iω<>	
RL0805	±1,500 ppm/°C	±1,200 ppr	m∕°C	±1,0	00 ppm/°C	±600 ppm/°C	±300 ppm/°C	±200 ppm/°C	
RL1206	±1,500 ppm/°C	±1,200 ppr	m/°C	±1,0	00 ppm/°C	±600 ppm/°C	±300 ppm/°C	±200 ppm/°C	
Π0mΩ≤R <iω< th=""><th>±1,500 ppm/°C</th><th>±1,000 ppr</th><th>m/°C</th><th>±80</th><th>0 ppm/°C</th><th>±600 ppm/°C</th><th>±300 ppm/°C</th><th>±200 ppm/°C</th></iω<>	±1,500 ppm/°C	±1,000 ppr	m/°C	±80	0 ppm/°C	±600 ppm/°C	±300 ppm/°C	±200 ppm/°C	
RL2010	±1,500 ppm/°C	±1,200 ppr	m∕°C	±1,0	00 ppm/°C	±600 ppm/°C	±300 ppm/°C	±200 ppm/°C	
RL2512	±1,500 ppm/°C	±1,200 ppr	m∕°C	±80	0 ppm/°C	±600 ppm/°C	±300 ppm/°C	±200 ppm/°C	
	I0mΩ≤R≤30mΩ	30mΩ<	<r≤56r< th=""><th>nΩ</th><th>56mΩ<r≤< th=""><th>I80mΩ</th><th>180mΩ<r<1ω< th=""><th></th></r<1ω<></th></r≤<></th></r≤56r<>	nΩ	56mΩ <r≤< th=""><th>I80mΩ</th><th>180mΩ<r<1ω< th=""><th></th></r<1ω<></th></r≤<>	I80mΩ	180mΩ <r<1ω< th=""><th></th></r<1ω<>		
RLI2I8 I0mΩ≤R <iω< th=""><td>±2,000 ppm/°C</td><td>±1,000</td><td>0 ppm/</td><td>°C</td><td>±700 pp</td><td>m/°C</td><td>±250 ppm/°C</td><td></td></iω<>	±2,000 ppm/°C	±1,000	0 ppm/	°C	±700 pp	m/°C	±250 ppm/°C		

FOOTPRINT AND SOLDERING PROFILES

For recommended footprint and soldering profiles, please see the special data sheet "Chip resistors mounting".

ENVIRONMENTAL DATA

For material declaration information (IMDS-data) of the products, please see the separated info "Environmental data".

PACKING STYLE AND PACKAGING QUANTITY

Table 3 Packing style and packaging quantity

	REEL DIMENSION	RL0402	RL0603	RL0805	RL1206	RL1210	RL1218	RL2010	RL2512
Paper/PE taping reel (R)	7" (178 mm)	10,000	5,000	5,000	5,000	5,000			
Embossed taping reel (K)	7" (178 mm)						4,000	4,000	4,000

NOTE

I. For Paper/PE/Embossed tape and reel specification/dimensions, please see the special data sheet "Packing" document.





Chip Resistor Surface MountRLSERIES0402 to 2512 (Pb Free)

FUNCTIONAL DESCRIPTION

OPERATINGTEMPERATURE RANGE

Range: -55°C to +125°C

POWER RATING

Each type rated power at 70°C: RL0402=1/16 W; RL0603=1/10 W; RL0805=1/8 W; RL1206=1/4 W; RL1210=1/2 W; RL1218=1 W; RL2010=3/4 W; RL2512=1 W.

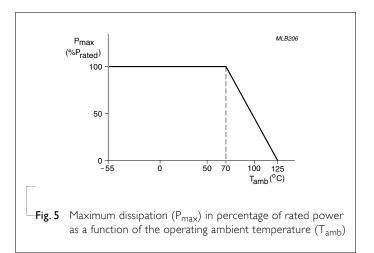
RATED VOLTAGE

The DC or AC (rms) continuous working voltage corresponding to the rated power is determined by the following formula:

$$V = \sqrt{P \times R}$$

Where

- V = Continuous rated DC or AC (rms) working voltage (V)
- P = Rated power (W)
- $R = Resistance value (\Omega)$





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TESTS AND REQUIREMENTS

Table 4 Test condition, procedure and requirements

EST	TEST METHOD	PROCEDURE	REQUIREMENTS		
Temperature Coefficient of	MIL-STD-202F-method 304;	At +25/–55 °C and +25/+125 °C	Refer to table 2		
Resistance (T.C.R.)	JIS C 5202-4.8	Formula:			
		T.C.R= $\frac{R_2 - R_1}{R_1(t_2 - t_1)} \times 10^6 \text{ (ppm/°C)}$			
		Where t_1 =+25 °C or specified room temperature			
		t_2 =–55 °C or +125 °C test temperature			
		R_1 =resistance at reference temperature in ohms			
		R_2 =resistance at test temperature in ohms			
Thermal Shock	MIL-STD-202F-method 107G; IEC 60115-1 4.19	At -65 (+0/-10) °C for 2 minutes and at +125 (+10/-0) °C for 2 minutes; 25 cycles	±1.0%		
Low	MIL-R-55342D-Para 4.7.4 At	At –65 (+0/–5) °C for I hour; RCWV applied	±1.0%		
Temperature Operation		for 45 (+5/–0) minutes	No visible damage		
Short Time	MIL-R-55342D-Para 4.7.5;	2.5 × RCWV applied for 5 seconds at room	±1.0% for 1% tol.		
Overload	IEC 60115-1 4.13	temperature	±2.0% for 5% tol.		
			No visible damage		
Insulation	MIL-STD-202F-method 302;	One DC voltage (V) applied for 1 minute	≥10 GΩ		
Resistance					
Resistance	IEC 60115-1 4.6.1.1	Details see below table 5			
Dielectric	IEC 60115-1 4.6.1.1 MIL-STD-202F-method 301;	Details see below table 5 One AC voltage (V _{rms}) applied for 1 minute	No breakdown or flashover		
			No breakdown or flashover		
Dielectric Withstand Voltage Resistance to	MIL-STD-202F-method 301;	One AC voltage (V _{ms}) applied for 1 minute Details see below table 5 Unmounted chips; 260 ±5 °C for 10 ±1	No breakdown or flashover ±1.0%		
Dielectric Withstand Voltage	MIL-STD-202F-method 301; IEC 60115-1 4.6.1.1	One AC voltage (V _{rms}) applied for 1 minute Details see below table 5			
Dielectric Withstand Voltage Resistance to Soldering	MIL-STD-202F-method 301; IEC 60115-1 4.6.1.1 MIL-STD-202F-method 210C;	One AC voltage (V _{ms}) applied for 1 minute Details see below table 5 Unmounted chips; 260 ±5 °C for 10 ±1	±1.0%		

Table 4 Test condition, procedure and requirements (continued)

EST	TEST METHOD	PROCEDURE	REQUIREMENTS
Solderability	MIL-STD-202F-method 208A;	Solder bath at 245±3 °C	Well tinned (≥95% covered)
	IEC 60115-1 4.17	Dipping time: 2±0.5 seconds	No visible damage
Resistance to	MIL-STD-202F-method 215;	lsopropylalcohol (C ₃ H ₇ OH) or dichloromethane	No smeared
Solvent	IEC 60115-1 4.29	(CH_2Cl_2) followed by brushing	
Humidity	JIS C 5202 7.5;	1,000 hours; 40±2 °C; 93(+2/–3)% RH	±2.0%
(steady state)	IEC 60115-8 4.24.8	RCWV applied for 1.5 hours on and 0.5 hour off	
Leaching	EIA/IS 4.13B;	Solder bath at 260±5 °C	No visible damage
5	IEC 60115-8 4.18	Dipping time: 30±1 seconds	0

Table 5 Criteria of rated continued working voltage and overload voltage

ТҮРЕ	RL0402	RL0603	RL0805	RL1206	RL1210	RL1218	RL2010	RL2512
Voltage (DC/unit: V); (AC/ unit: V _{rms})	100	100	300	500	500	500	500	500

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<u>REVISION HISTORY</u>

REVISION	DATE	CHANGE NOTIFICATION	DESCRIPTION
Version 2	Jul 15, 2005	-	- Ordering example revised
Version I	Apr 15, 2005	-	- Size 1218 extended
			- Test method and procedure updated
			- PE tape added (paper tape will be replaced by PE tape)
Version 0	Nov. 10, 2003	-	- First issue of this specification

